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John T.  
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TECHNOLOGY CENTER 2800

Attorney Docket No. 254-082/D1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent App. No.: 10/092,104  
Title: Contact Member Stacking System and Method  
Inventor: James Douglas Wehrly, Jr.  
Examiner and Art: Paul E. Brock II - Art Unit 2815  
Filing Date: March 6, 2002

AFFIDAVIT OF JAMES G. WILDER UNDER 37 CFR § 1.132

Assistant Commissioner of Patents  
Washington, D.C. 20231

Before me, the undersigned authority, personally appeared JAMES G. WILDER, who being by me duly sworn, deposed as follows:

My name is JAMES G. WILDER. I am of sound mind, capable of making this affidavit, and personally acquainted with the facts herein stated:

1. I am a senior engineering manager employed by Staktek Group, L. P.
2. I have been an engineer for 24 years in the field of packaging and stacking technologies. As such, I have worked for years with soldering and solder-containing compounds as used in the assembly of stacked modules composed of integrated circuits. In particular, I am familiar with the knowledge typically possessed by a person of ordinary skill in the field of creating stacked integrated circuit modules.
3. I have read U.S. Pat. App. No. 10/092,104 entitled "Contact Member Stacking System and Method" as published as US 2002/0142515 A1 dated Oct. 3, 2002 (the "published application"). I have studied Figs. 1-11 that are part of the published application. I have read claims 1-4 of the published application.
4. As described in paragraphs [0042] and [0043] of the published application, a preferred method for constructing a stack of integrated circuits is provided that includes the application of a solder paste (lines 3-4 of paragraph 0042) to one side of the carrier panel 52. Paragraph 0043 describes the application of solder paste to the other side of the carrier panel. As explained in the published application, this application of solder paste to the carrier panel realizes application of the solder paste to the members of the carrier panel that will become the contact members 24.

5. Those of skill in my field would understand that the solder paste referred to in paragraphs [0042, 0043] is a solder-containing compound. The application literally says this at paragraph 0042.

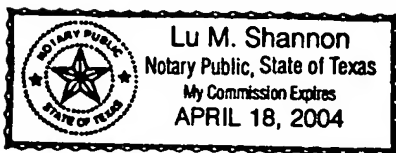
6. Those of skill in my field would understand the paragraph 0042 description of application of the solder paste to the carrier panel as an instance of applying a solder-containing compound to the first side of the members as recited in and in the context of the invention recited in claim 1 of the published application. Those of skill in my field would understand the invention claimed in claim 1 without any need for any further explanatory drawing or figure related to the solder containing compound or its application as recited in that claim. It is very well understood in my field as to how to apply solder containing compounds to lead frame materials just as solder containing compounds are well understood.

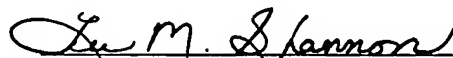
7. Those of skill in my field would understand the paragraph 0043 description of application of solder paste to the "lower surface" of carrier panel 52 as an instance of applying a solder-containing compound to the second side of the members. Those of skill in my field would understand the invention recited in claim 1 without any need for any further explanatory drawing or figure related to the solder containing compound or its application as recited in that claim.

  
Affiant

James G. Wilder  
Affiant's Printed Name

SWORN TO AND SUBSCRIBED before me on the 27<sup>TH</sup> day of January, 2003



  
NOTARY PUBLIC  
Notary's Printed Name: Lu M. SHANNON  
My Commission Expires: 4-18-2004